RGTV80TK65D

650V 40A Field Stop Trench IGBT

Datasheet

V _{CES}	650V
I _{C (100°C)}	23A
V _{CE(sat) (Typ.)}	1.5V
P_{D}	85W

Outline TO-3PFM

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) High Speed Switching & Low Switching Loss
- 3) Short Circuit Withstand Time 2µs
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb free Lead Plating; RoHS Compliant

Application

Solar Inverter

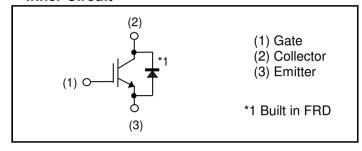
UPS

Welding

ΙH

PFC

●Inner Circuit



Packaging Specifications

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	Packaging	Tube			
	Reel Size (mm)	-			
Type	Tape Width (mm)	-			
Type	Basic Ordering Unit (pcs)	450			
	Packing Code	C11			
	Marking	RGTV80TK65D			

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	650	V
Gate - Emitter Voltage		V _{GES}	±30	V
Callagton Commant	T _C = 25°C	I _C	39	Α
Collector Current	T _C = 100°C	I _C	23	Α
Pulsed Collector Current	Pulsed Collector Current		160	Α
D: 1 5 10 1	T _C = 25°C	I _F	40	Α
Diode Forward Current	T _C = 100°C	I _F	23	Α
Diode Pulsed Forward Current		I _{FP} *1	160	Α
	T _C = 25°C	P _D	85	W
Power Dissipation	T _C = 100°C	P _D	42	W
Operating Junction Temperature		T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{imax.}

●Thermal Resistance

Parameter	Symbol	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	1.75	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	2.00	°C/W

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions		Unit		
i arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_{C} = 10 \mu A, V_{GE} = 0 V$	650	ı	ı	V
Collector Cut - off Current	I _{CES}	$V_{CE} = 650V, V_{GE} = 0V$	ı	ı	10	μΑ
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V$, $V_{CE} = 0V$	1	1	±200	nA
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5V, I_{C} = 27.5 \text{mA}$	5.0	6.0	7.0	V
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_{C} = 40A, V_{GE} = 15V,$ $T_{j} = 25^{\circ}C$ $T_{j} = 175^{\circ}C$	-	1.5 1.85	1.9 -	٧

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions		Unit		
			Min.	Тур.	Max.	Offic
Input Capacitance	C _{ies}	$V_{CE} = 30V$,	-	2370	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$,	-	94	-	pF
Reverse transfer Capacitance	C _{res}	f = 1MHz	-	38	-	
Total Gate Charge	Q_g	$V_{CE} = 400V$,	-	81	-	
Gate - Emitter Charge	Q_ge	$I_{\rm C} = 40A$,	-	17	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	31	-	
Turn - on Delay Time	t _{d(on)}		-	39	-	
Rise Time	t _r	$I_{C} = 40A, V_{CC} = 400V,$ $V_{GE} = 15V, R_{G} = 10\Omega,$	-	17	-	20
Turn - off Delay Time	t _{d(off)}	$T_i = 25^{\circ}C$	-	113	-	ns
Fall Time	t _f	Inductive Load	-	45	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	1.02	-	mJ
Turn - off Switching Loss	E _{off}	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	-	0.71	-	
Turn - on Delay Time	t _{d(on)}	$I_{C} = 40A, V_{CC} = 400V,$ $V_{GE} = 15V, R_{G} = 10\Omega,$	-	38	-	ns
Rise Time	t _r		-	19	-	
Turn - off Delay Time	t _{d(off)}	$T_i = 175^{\circ}C$	-	130	-	
Fall Time	t _f	Inductive Load	-	86	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	1.07	-	mJ
Turn - off Switching Loss	E _{off}		-	1.01	-	1110
Reverse Bias Safe Operating Area	RBSOA	$I_C = 160A$, $V_{CC} = 520V$, $V_P = 650V$, $V_{GE} = 15V$, $R_G = 100\Omega$, $T_j = 175^{\circ}C$	FULL SQUARE		-	
Short Circuit Withstand Time	t _{sc}	$V_{CC} \le 360V$, $V_{GE} = 15V$, $T_j = 25^{\circ}C$	2	-	-	μs

•FRD Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Cymphal	Conditions	Values			Llait
	Symbol		Min.	Тур.	Max.	Unit
		$I_F = 40A$,				
Diode Forward Voltage	V_{F}	$T_j = 25^{\circ}C$	-	1.45	1.9	V
		$T_j = 175$ °C	-	1.55	-	
Diode Reverse Recovery Time	t _{rr}		-	101	-	ns
Diode Peak Reverse Recovery Current	I _{rr}	I _F = 40A, V _{CC} = 400V,	-	9.6	-	Α
Diode Reverse Recovery Charge	Q _{rr}	di _F /dt = 200A/µs, T _j = 25°C	-	0.53	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	25.1	-	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 40A$, $V_{CC} = 400V$, $di_F/dt = 200A/\mu s$, $T_j = 175$ °C	-	184	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	13.1	-	Α
Diode Reverse Recovery Charge	Q _{rr}		-	1.42	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	102.5	-	μJ

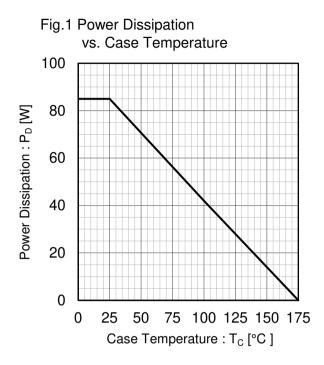


Fig.2 Collector Current vs. Case Temperature 50 40 Collector Current : Ic [A] 30 20 10 T_j ≤ 175°C V_{GE} ≥ 15V 0 25 50 75 100 125 150 175 Case Temperature: T_C [°C]

Fig.3 Forward Bias Safe Operating Area

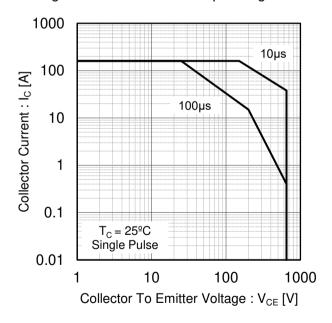


Fig.4 Reverse Bias Safe Operating Area

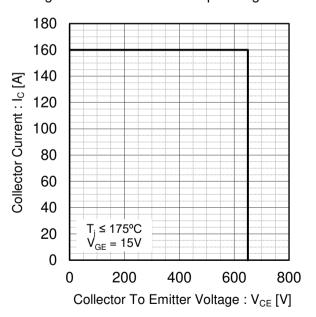


Fig.5 Typical Output Characteristics

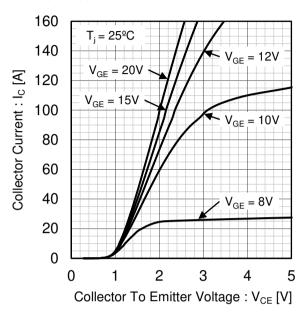


Fig.6 Typical Output Characteristics

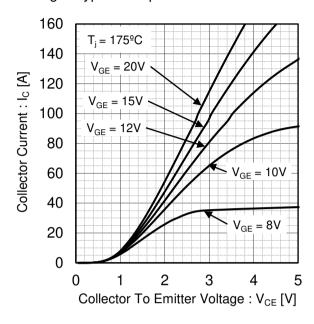


Fig.7 Typical Transfer Characteristics

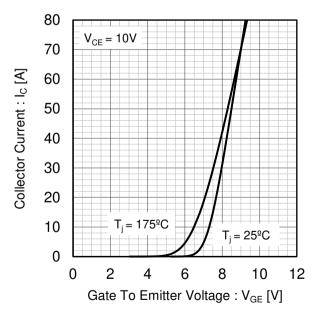
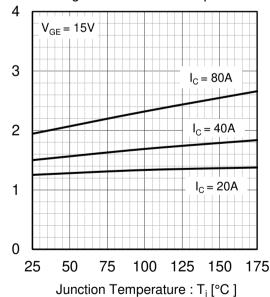


Fig.8 Typical Collector to Emitter Saturation Voltage vs. Junction Temperature



Collector To Emitter Saturation

Voltage: V_{CE(sat)} [V]



Fig.9 Typical Collector to Emitter Saturation Voltage vs. Gate to Emitter Voltage

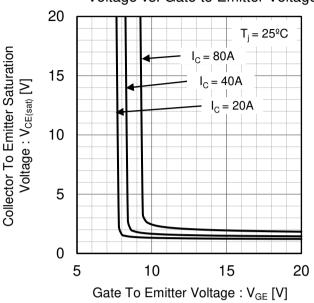


Fig.10 Typical Collector to Emitter Saturation Voltage vs. Gate to Emitter Voltage

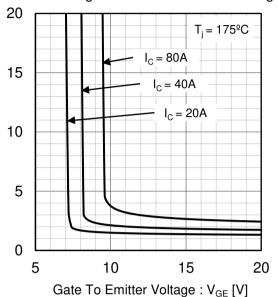


Fig.11 Typical Switching Time vs. Collector Current

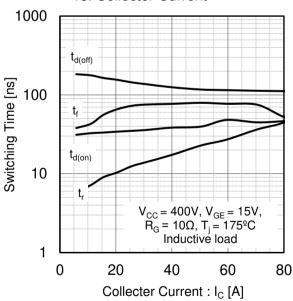
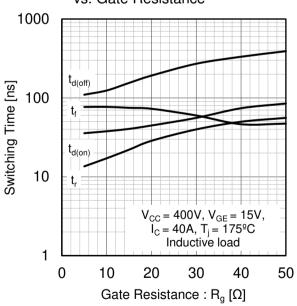


Fig.12 Typical Switching Time vs. Gate Resistance



Collector To Emitter Saturation

Voltage: V_{CE(sat)} [V]

Fig.13 Typical Switching Energy Losses vs. Collector Current

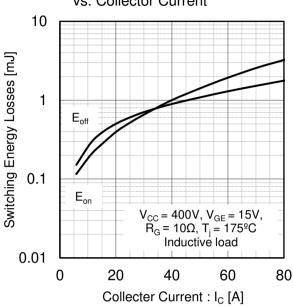


Fig.14 Typocal Switching Energy Losses vs. Gate Resistance

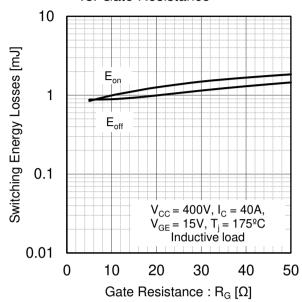


Fig.15 Typical Capacitance vs. Collector to Emitter Voltage

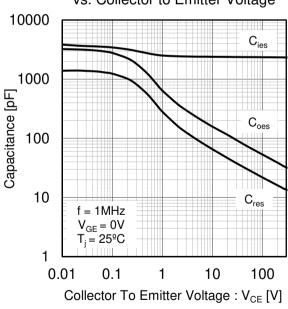


Fig.16 Typical Gate Charge

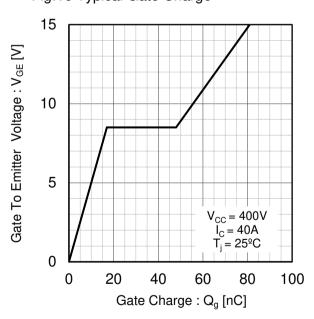


Fig.17 Typical Diode Forward Current vs. Forward Voltage

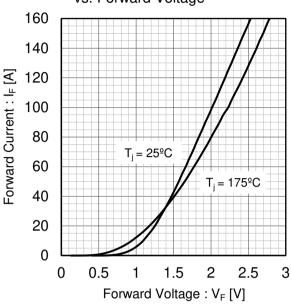


Fig.18 Typical Diode Revese Recovery Time vs. Forward Current

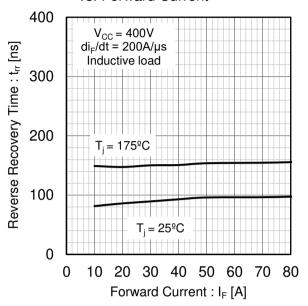


Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

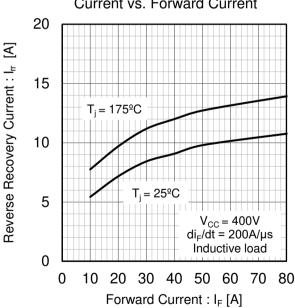


Fig.20 Typical Diode Rrverse Recovery Charge vs. Forward Current

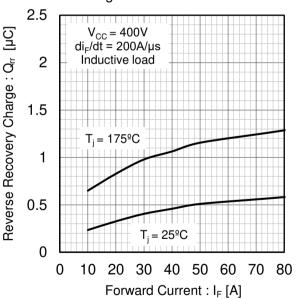


Fig.21 Typical IGBT Transient Thermal Impedance

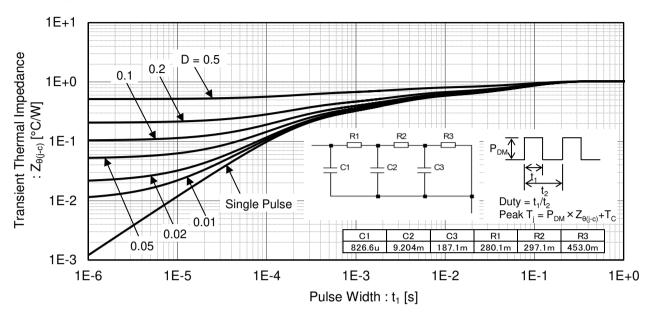
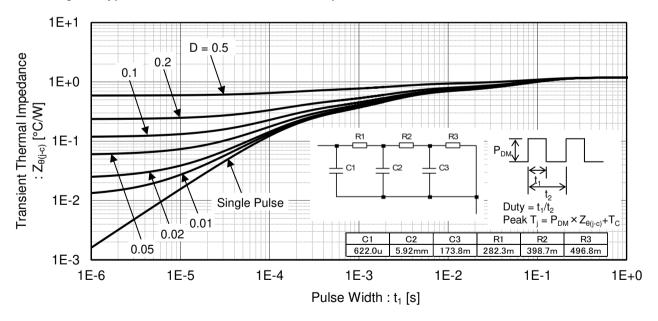


Fig.22 Typical Diode Transient Thermal Impedance



●Inductive Load Switching Circuit and Waveform

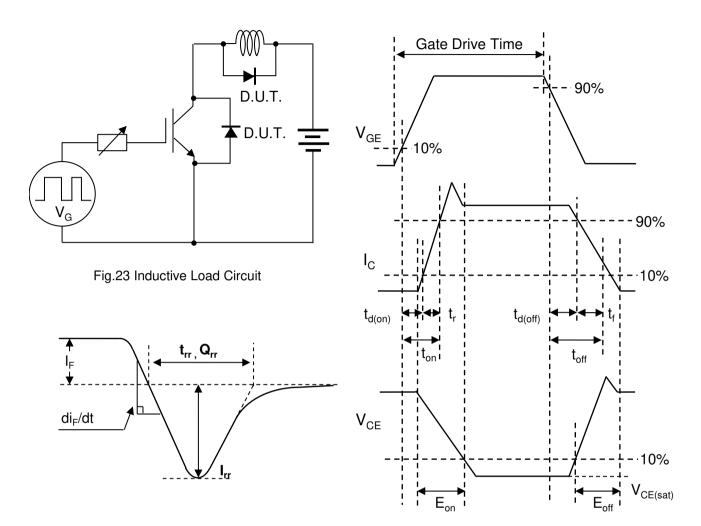


Fig.25 Diode Reverse Recovery Waveform

Fig.24 Inductive Load Waveform

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